

Intel® Open Source HD Graphics Programmers' Reference Manual (PRM)

Volume 4: Configurations

For the 2014-2015 Intel Atom™ Processors, Celeron™ Processors and Pentium™ Processors based on the "Cherry Trail/Braswell" Platform
(Cherryview/Braswell graphics)

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Configurations Overview

The Intel "Gen" Graphics Architecture was first introduced to the market in 2004. Since that time, the architecture and its implementation have evolved to add many new features, increase performance, and improve power efficiency. This volume of the PRM tracks the Gen graphics evolution. It also provides information over time about changes to architectural attributes, feature sets, and performance.

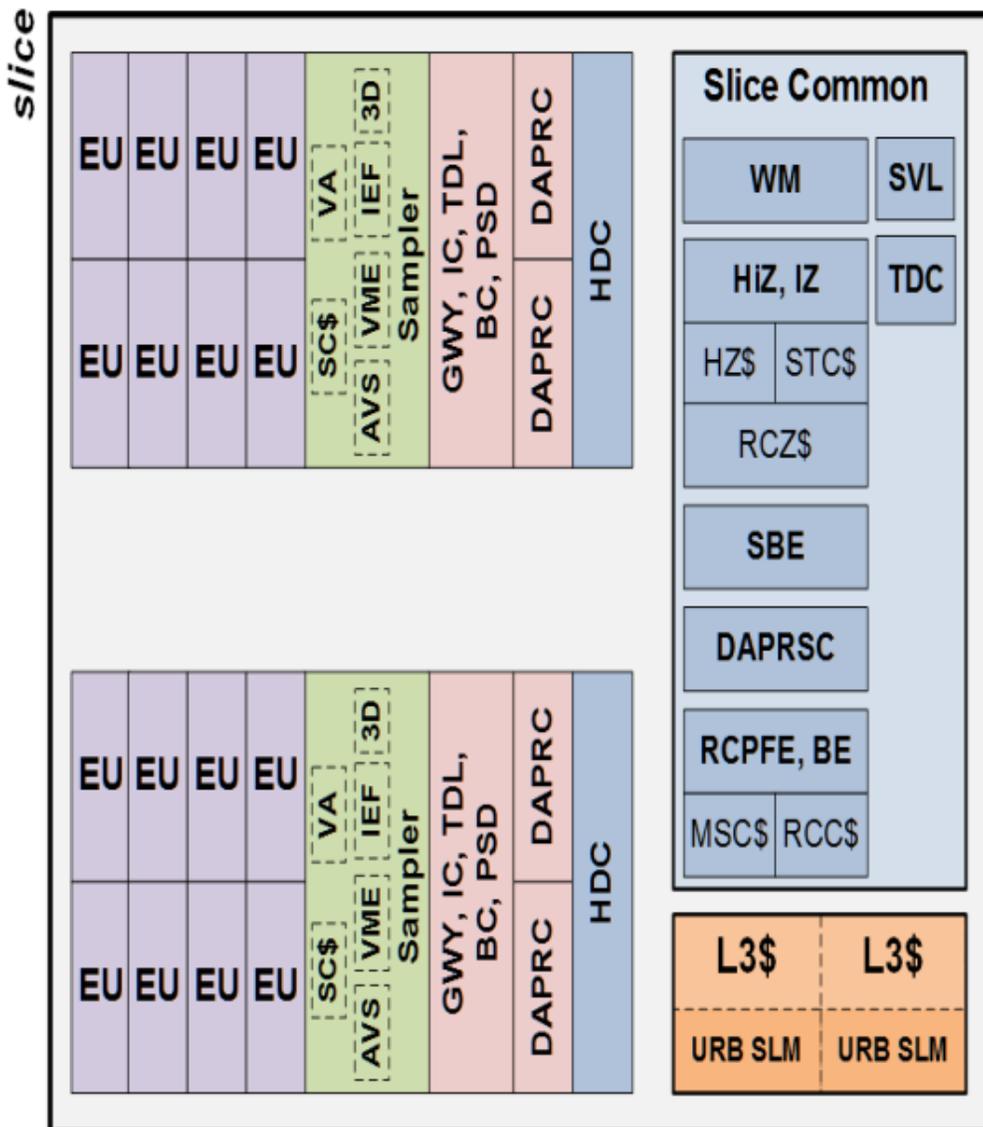
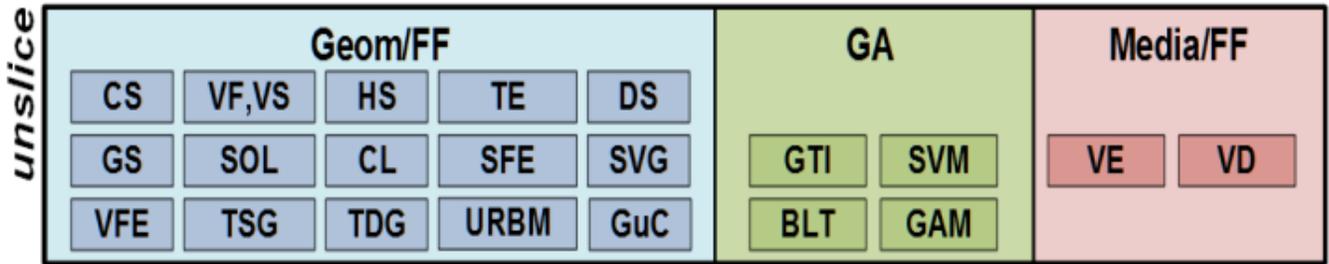
Configurations

This chapter contains configurations details as described in the following sections:

- Top Level Block Diagrams
- Device Attributes

Top Level Block Diagrams

The diagram below shows basic feature blocks of the Cherryview (CHV) graphics architecture:



This diagram is based on the following functional partitions:

- (a) Geometry Fixed Functions (Geom/FF)
- (b) Media Fixed Functions (Media/FF)
- (c) Global Assets and GT Interface (GA)
- (d) One or more Subslices (two shown)
- (e) A Slice Common block
- (f) An L3 Cache (L3\$) block

Note that the combination of (a), (b), and (c) is typically referred to as the “unslice”, while a combination of (d), (e), and (f) is referred to as a compute “slice”.

The functionality in each of these groupings is further broken down as follows:

- Unslice – Fixed function pipelines for 3D, GPGPU, and Media operations, and interface to the outside world.
 - The 3D Geometry / Fixed Function (Geom/FF) block consisting of:
 - 3D fixed function pipeline (CS, VFVS, HS, TE, DS, GS, SOL, SL, SFE, SVG)
 - Video Front-End unit (VFE)
 - Thread Spawner unit (TSG) and the global Thread Dispatcher unit (TDG)
 - Unified Return Buffer Manager (URBM)
 - Media fixed function assets:
 - Video Decode (VD) Box
 - Video Encode (VE) Box
 - The Global Assets (GA) block as the primary interface and memory stream gateway to the outside world, consisting of:
 - GT Interface (GTI)
 - State Variable Manager (SVM)
 - Blitter (BLT)
 - Graphics Arbiter (GAM)
- Subslice (three shown) – A compute unit with supporting fixed- or shared-function assets sufficient for the EU capability.
 - A bank of Execution Units (EUs) – eight per subslice shown
 - Sampler, supporting both media and 3D functions
 - Gateway (GWY)
 - Instruction cache (IC)
 - Local Thread Dispatcher (TDL)
 - Barycentric Calculator (BC)
 - Pixel Shader Dispatcher (PSD)

- Data Cluster (HDC)
- Dataport Render Cache (DAPRC) - two per subslice
- Slice Common – Scalable fixed function assets which support the compute horsepower provided two or more subslices.
 - 3D Fixed Function:
 - Windower/Mask unit (WM)
 - Plane-Z, Hi-Z (HZ) and Intermediate Z (IZ)
 - Setup Backend (SBE)
 - Pixel backend units
 - 3D stream caches for color, multi-sample surface, iz, and stencil (RCC\$, MSC\$, HZ\$, RCZ\$, STC\$)
 - Media Fixed Function:
 - DAPRSC
 - RCPFE, BE
 - SVL
 - TDC
- L3 Cache – backing L3 cache for certain memory streams emanating from subslices.
 - L3 Data cache with support for data, URB, and shared local memory (SLM)

Device Attributes

Product Configuration Attribute Table			
Product Family	CHV		
Architectural Name	2x4	2x6	2x8
SKU Name			
Global Attributes			
Slice count	1	1	1
Subslice Count	2	2	2
EU/Subslice	4	6	8
EU count (total)	8	12	16
Thread Count	7	7	7
Thread Count (Total)	56	84	112
FLOPs/Clk - Half Precision, MAD (peak)	256	384	512
FLOPs/Clk - Single Precision, MAD (peak)	128	192	256
FLOPs/Clk - Double Precision, MAD (peak)	16	24	32
Unslice clocking (coupled/decoupled from Cr slice)	coupled [1]	coupled [1]	coupled [1]
GTI / Ring Interfaces	1	1	1
GTI bandwidth (bytes/unslice-clk)	64: R	64: R	64: R
	64: W	64: W	64: W
Caches & Dedicated Memories			
L3 Cache, total size (bytes)	384K	384K	384K
L3 Cache, bank count	2	2	2
L3 Cache, bandwidth (bytes/clk)			
L3 Cache, D\$ Size (Kbytes)	192K-256K	192K-256K	192K-256K
URB Size (kbytes)	64K-192K	64K-192K	64K-192K
SLM Size (kbytes)	0, 128K	0, 128K	0, 128K
LLC/L4 size (bytes)	N/A	N/A	N/A
Instruction Cache (IC, bytes)	2x 48K	2x 48K	2x 48K
Color Cache (RCC, bytes)	24K	24K	24K
MSC Cache (MSC, bytes)	12K	12K	12K
HiZ Cache (HZC, bytes)	8K	8K	8K
Z Cache (RCZ, bytes)	16K	16K	16K
Stencil Cache (STC, bytes)	4K	4K	4K
L1 Texture Cache (bytes)	2x 32K	2x 32K	2x 32K
MT Texture Cache (bytes)	2x 8K	2x 8K	2x 8K

Product Configuration Attribute Table			
Instruction Issue Rates			
FMAD, SP (ops/EU/clock)	8	8	8
FMUL, SP (ops/EU/clock)	8	8	8
FADD, SP (ops/EU/clock)	8	8	8
MIN,MAX, SP (ops/EU/clock)	8	8	8
CMP, SP (ops/EU/clock)	8	8	8
INV, SP (ops/EU/clock)	2	2	2
SQRT, SP (ops/EU/clock)	2	2	2
RSQRT, SP (ops/EU/clock)	2	2	2
LOG, SP (ops/EU/clock)	2	2	2
EXP, SP (ops/EU/clock)	2	2	2
POW, SP (ops/EU/clock)	1	1	1
IDIV, SP (ops/EU/clock)	1-6	1-6	1-6
TRIG, SP (ops/EU/clock)	2	2	2
FDIV, SP (ops/EU/clock)	1	1	1
Load/Store			
Data Ports (HDC)	2	2	2
L3 Load/Store - same addresses within msg (dwords/clock)	2x 32	2x 32	2x 32
L3 Load/Store - unique addresses within msg (dwords/clock)			
SLM Load//Store - same addresses within msg (dwords/clock)			
SLM Load//Store - unique addresses within msg (dwords/clock)			
Atomic, Local 32b - same addresses within msg (dwords/clock)	2x 16	2x 16	2x 16
Atomic, Global 32b - unique addresses within msg (dwords/clock)	2x 16	2x 16	2x 16
3D Attributes			
Geometry pipes	1	1	1
Samplers (3D)	2	2	2
Texel Rate, point, 32b (tex/clock)	8	8	8
Texel Rate, point, 64b (tex/clock)	8	8	8
Texel Rate, point, 128b (tex/clock)	8	8	8
Texel Rate, bilinear, 32b (tex/clock)	8	8	8
Texel Rate, bilinear, 64b (tex/clock)	8	8	8
Texel Rate, bilinear, 128b (tex/clock)	2	2	2
Texel Rate, trilinear, 32b (tex/clock)	4	4	4
Texel Rate, trilinear, 64b (tex/clock)	2	2	2
Texel Rate, trilinear, 128b (tex/clock)	1	1	1
Texel Rate, aniso 2x, 32b (tex/clock)	2	2	2

Product Configuration Attribute Table			
Texel Rate, aniso 4x, 32b (tex/clock)	1	1	1
Texel Rate, aniso 8x, 32b (tex/clock)	0.5	0.5	0.5
Texel Rate, aniso 16x, 32b (tex/clock)	0.25	0.25	0.25
HiZ Rate, (ppc)	32	32	32
IZ Rate, (ppc)	16	16	16
Stencil Rate (ppc)	32	32	32
<i>(500 MHz, DDR-1600 or eDRAM; Range depends on dynamic compression ratio)</i>			
Pixel Rate, fill, 32bpp (pix/clock, RCC hit)	4	4	4
Pixel Rate, fill, 32bpp (pix/clock, LLC hit @ 1.0x unslice clock)	N/A	N/A	N/A
Pixel Rate, fill, 32bpp (pix/clock, LLC hit, @ 1.5x unslice clock)	N/A [1]	N/A [1]	N/A [1]
Pixel Rate, fill, 32bpp (pix/clock, memory, @ 1.0x unslice clock)	4	4	4
Pixel Rate, fill, 32bpp (pix/clock, memory, @ 1.5x unslice clock)	N/A [1]	N/A [1]	N/A [1]
<i>(500 MHz, DDR-1600 or eDRAM; Range depends on dynamic compression ratio)</i>			
Pixel Rate, blend, 32bpp (p/clock, RCC hit)	4	4	4
Pixel Rate, blend, 32bpp (p/clock, LLC hit, @ 1.0x unslice clock)	N/A	N/A	N/A
Pixel Rate, blend, 32bpp (p/clock, LLC hit, @ 1.5x unslice clock)	N/A [1]	N/A [1]	N/A [1]
Pixel Rate, blend, 32bpp (pix/clock, memory, @ 1.0x unslice clock)	4	4	4
Pixel Rate, blend, 32bpp (pix/clock, memory, @ 1.5x unslice clock)	N/A [1]	N/A [1]	N/A [1]
Media Attributes			
Samplers (media)	2	2	2
VDBox Instances	1	1	1
VEBox Instances	1	1	1
SFC Instances	N/A	N/A	N/A
WDBox Instances	N/A	N/A	N/A
WGBox Instances	N/A	N/A	N/A

Programming Note	
Context:	Device Attributes
Unslice clock and slice clock are coupled; independent frequency control is not supported.	